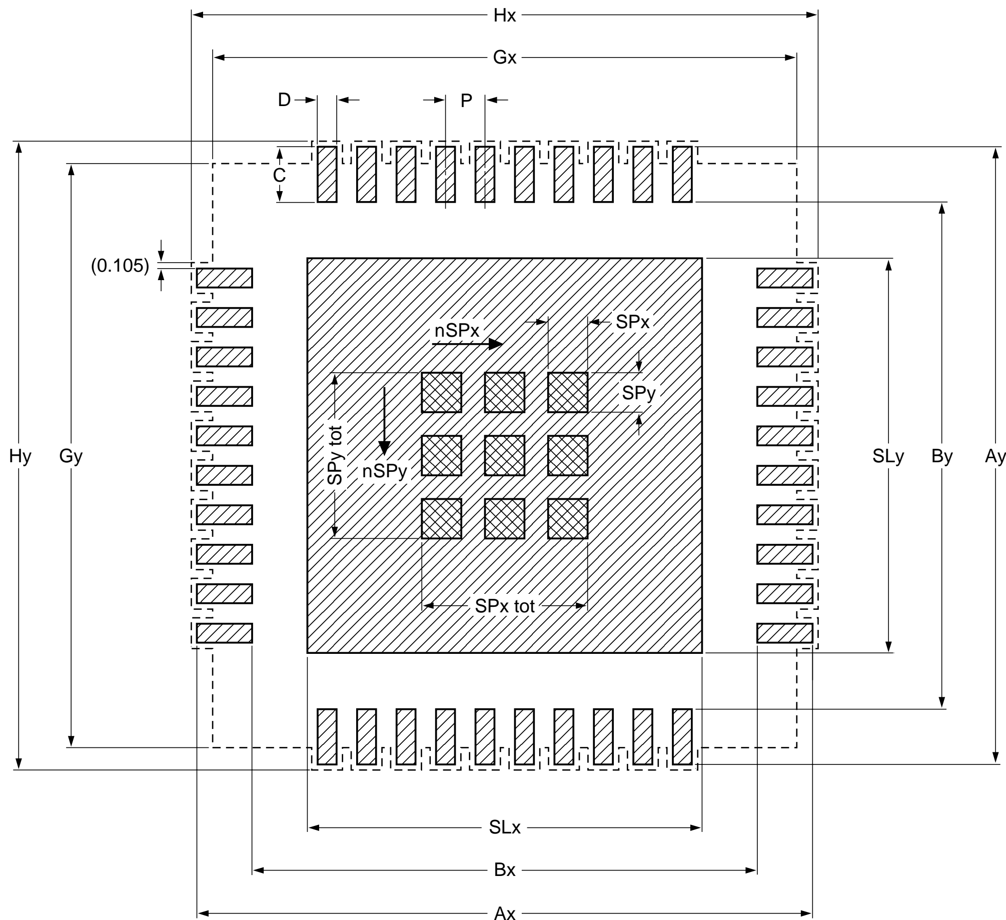
Footprint information for reflow soldering of HVQFN24 package **SOT616-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

solder paste deposit

solder land plus solder paste

occupied area

nSPx	nSPy
2	2

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	5.000	5.000	3.200	3.200	0.900	0.240	2.100	2.100	1.200	1.200	0.450	0.450	4.300	4.300	5.250	5.250

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